

SOT817-1

plastic thermal enhanced very thin quad flat package; no leads; 100 terminals; body 12 x 12 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN100
Package type industry code	HVQFN100
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	13-6-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	100	-	

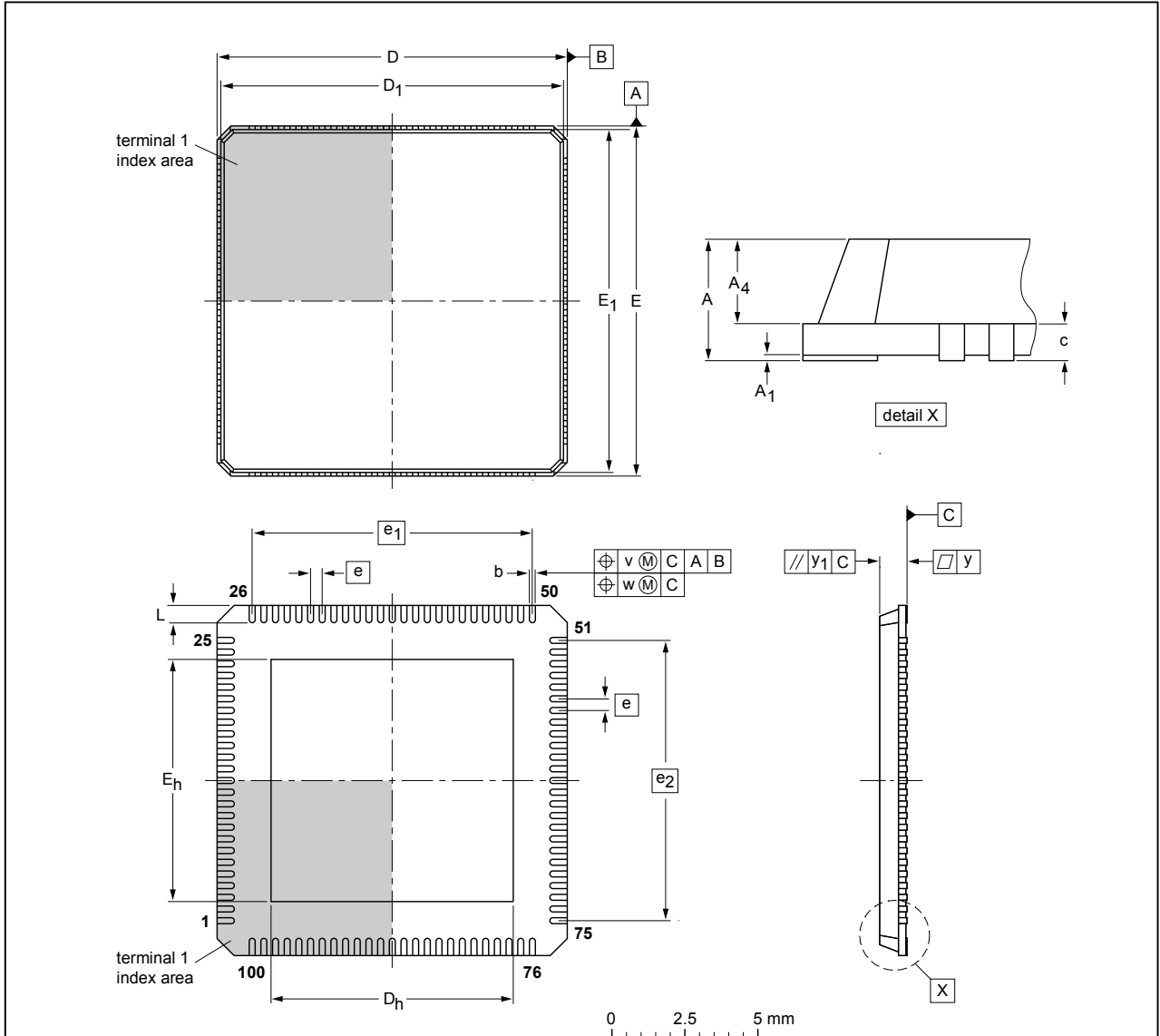


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2. Package outline

HVQFN100: plastic thermal enhanced very thin quad flat package; no leads; 100 terminals; body 12 x 12 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₄	b	c	D	D ₁	D _h	E	E ₁	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.80 0.65	0.27 0.16	0.2	12.1 11.9	11.8 11.7	8.5 8.1	12.1 11.9	11.8 11.7	8.5 8.1	0.4	9.6	9.6	0.7 0.5	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT817-1	---	MO-220	---			03-06-13

Fig. 1. Package outline HVQFN100 (SOT817-1)

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3. Soldering

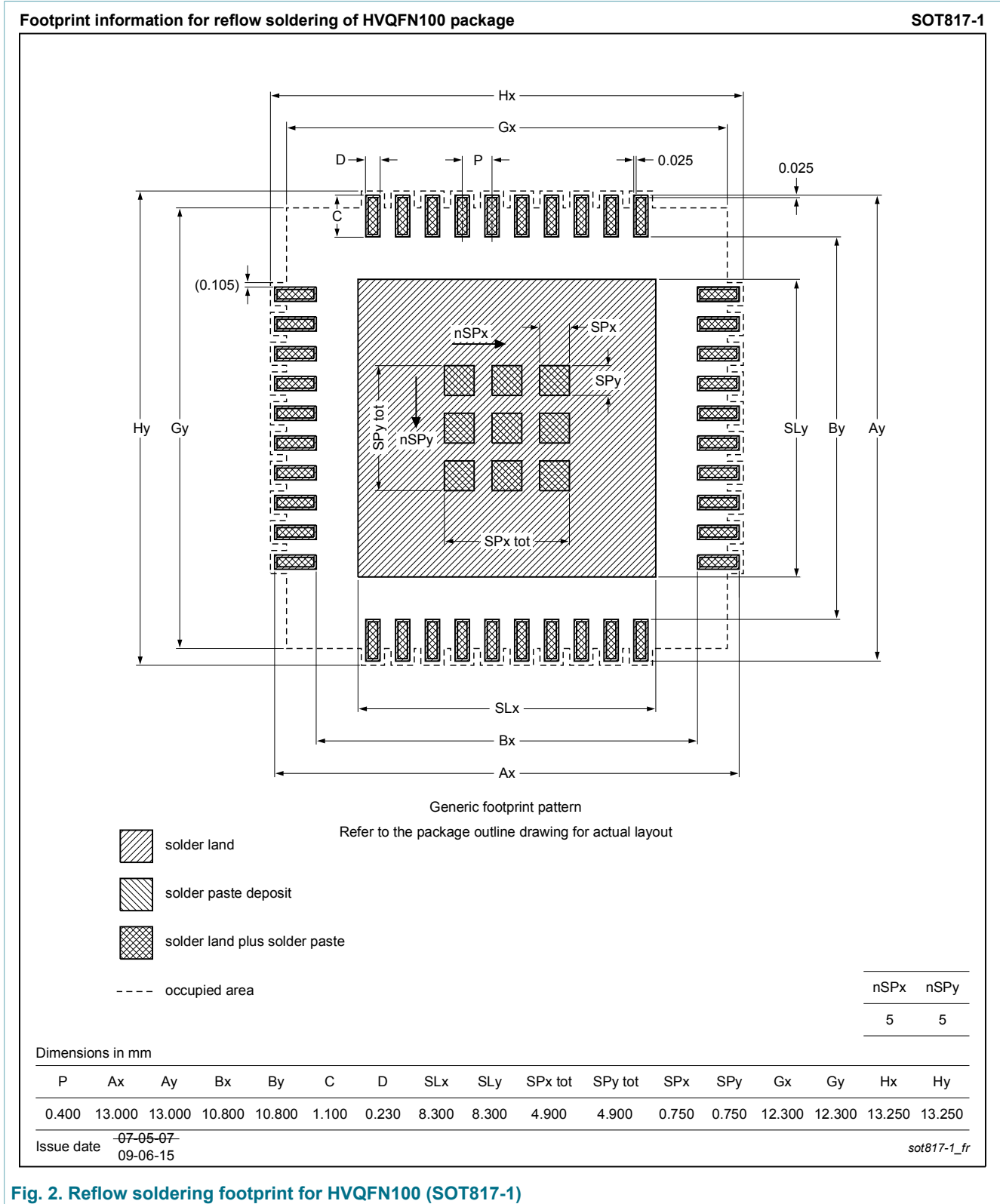


Fig. 2. Reflow soldering footprint for HVQFN100 (SOT817-1)

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4. Legal information

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